

NOT MEASUREMENT  
SENSITIVE

MIL-PRF-31032B  
SUPPLEMENT 1  
31 January 2010

## PERFORMANCE SPECIFICATION

### PRINTED CIRCUIT BOARD/PRINTED WIRING BOARD, GENERAL SPECIFICATION FOR

This supplement forms a part of [MIL-PRF-31032](#), dated 31 January 2010.

### SPECIFICATION SHEETS

- [MIL-PRF-31032/1](#) – Printed Wiring Board, Rigid, Multilayered, Thermosetting Resin Base Material, With or Without Blind and Buried Plated Through Holes, for Soldered Part Mounting.
- [MIL-PRF-31032/2](#) – Printed Wiring Board, Rigid, Single and Double Layer, Thermosetting Resin Base Material, With or Without Plated Through Holes, for Soldered Part Mounting.
- [MIL-PRF-31032/3](#) – Printed Wiring Board, Flexible, Single and Double Layer, With or Without Plated Through Holes, With or Without Stiffeners, for Soldered Part Mounting.
- [MIL-PRF-31032/4](#) – Printed Wiring Board, Rigid Flex or Flexible, Multilayer, With Plated Holes, With or Without Stiffeners, for Soldered Part Mounting.
- [MIL-PRF-31032/5](#) – Printed Wiring Board, Rigid, Multilayered, Thermoplastic or Thermoplastic and Thermosetting Resin Base Material, With Plated Through Holes, for High Frequency Applications.
- [MIL-PRF-31032/6](#) – Printed Wiring Board, Rigid, Single and Double Sided, Thermoplastic Resin Base Material, With or Without Plated Through Holes, for High Frequency Applications.

Custodians:  
Army – CR  
Navy – EC  
Air Force – 85  
DLA – CC

Preparing activity:  
DLA – CC  
  
(Project 5998-2009-045)

Review activities:  
Army – MI  
Navy – MC  
Air Force – 99

NOTE: The activities listed above were interested in this document as of the date of this document. Since organizations and responsibilities can change, you should verify the currency of the information above using the ASSIST Online database at <https://assist.daps.dla.mil/>.